

SPECIFICATION FOR APPROVAL

CUSTOMER	益力嘉
CUST. PART NO.	
CUST. DOC. REV.	
DESCRIPTION	CHIP INDUCTORS (RoHS+H.F.)
SAMPLE LOT NO.	S201911-0195
PART NO.	0805F-4R7K-DLRH01
DOC. REV.	ORIG
DATE	2019/11/26

Once you approve this part, please sign and return this page to the following marked location.

Customer Signature: _____ Date: _____

This part currently development section. Production line can produce this series of products.

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<i>Martin Wu</i>	<i>Adam Lee</i>	<i>K.C. Tseng</i>

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SPECIFICATION FOR APPROVAL

CUSTOMER 益力嘉	CUSTOMER P/N	REV. -	SPL. LOT NO. S201911-0195	
PART NAME CHIP INDUCTORS (RoHS+H.F.)	PART NO. 0805F-4R7K-DLRH01	REV. ORIG	DATE OF ISSUE 2019/11/26	Q'TY 5 PCS

ENGINEERING CHANGE NOTICE – RECORD

REVISION NO.	REVISION DESCRIPTION	AUTHOR	DATE	REMARK
ORIG		Adam Lee	2019/11/26	

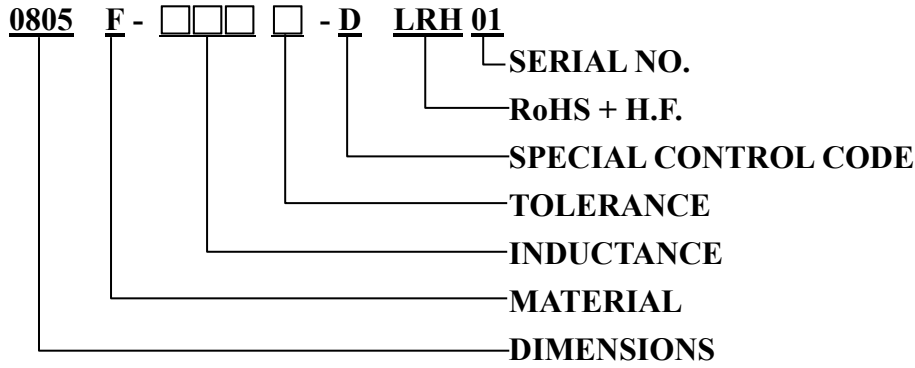


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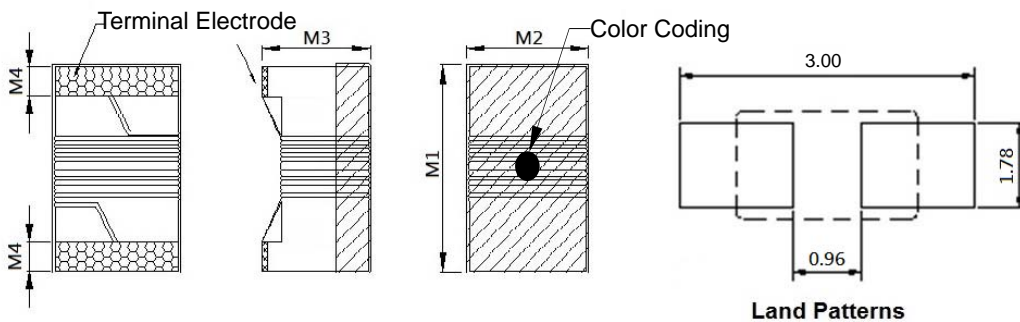
※This is a RoHS and REACH compliant product whose related documents are available on request.
 ※Graphic is only for dimensionally application.

1. SCOPE: THIS SPECIFICATION APPLIES TO WIRE WOUND CHIP INDUCTORS.

2. PART NUMBERING IDENTIFICATION



3. MECHANICAL DIMENSION



UNIT: mm

	DIM.	TOL.
M1	2.20	±0.2
M2	1.45	±0.2
M3	1.30	±0.1
M4	0.44	REF.

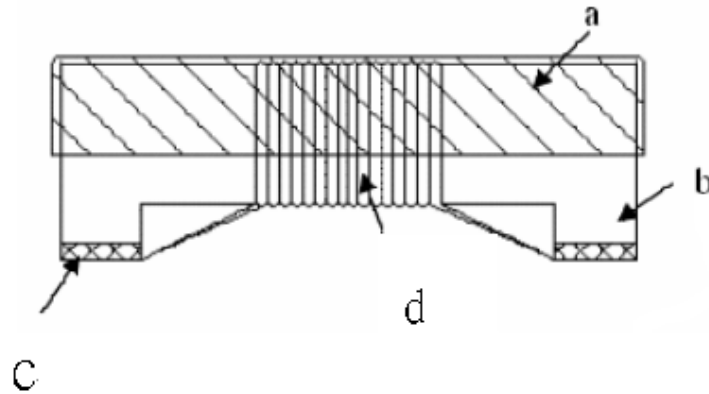
4. RATING TEMPERATURE

OPERATING TEMPERATURE RANGE: -40°C~+125°C (Including self - temperature rise)

STORAGE TEMPERATURE RANGE: -40°C~+125°C (on board)

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5. STRUCTURE



6. MATERIAL LIST

ITEM	MATERIAL CATEGORY	MATERIAL TYPE
a	Upper Plate	UV Glue
b	Core	Ferrite Core
c	Termination	Ag/Ni/Sn
d	Wire	Enameled Copper Wire

7. TEST INSTRUMENT

7-1. Inductance、Q: Agilent-4291, Agilent-4287, Agilent-E4991A, Agilent-4192, Agilent-4285

7-2. SRF: Agilent-4291, Agilent-E4991A, Agilent-4192

7-3. DC Resistance: Agilent-34420A

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8. ELECTRICAL SPECIFICATION

Part number	Inductance (μH)	Inductance Tolerance	Test Frequency (V/MHz)	Q TYP.	Test Frequency (MHz)	SRF (MHz) TYP.	DC Resistance (Ω) ±30%	Idc (mA) TYP.	Irms (mA) TYP.
0805F-4R7K-DLRH01	4.7	K	0.5/7.9	14	7.9	51	0.43	520	840

NOTE:

1. Tolerance: K:±10%
2. Idc: Applied the current to coils, the inductance change shall be less than 10% to initial value.
3. Heat Rated Current (Irms) will cause the coil temperature rise $\Delta T \leq 25^{\circ}\text{C}$ without core loss.
4. MSL: Level 1



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9. RELIABILITY PERFORMANCE

Item	Performance	Test Condition
Life Test		Preconditioning: Run through IR reflow for 2 times. (IPC/JEDECJ-STD-020DClassification Reflow Profiles) Temperature: 125±2°C Applied current: rated current Duration: 1000±12hrs Measured at room temperature after placing for 24±2 hrs.
Load Humidity		Preconditioning: Run through IR reflow for 2 times. (IPC/JEDECJ-STD-020DClassification Reflow Profiles) Humidity: 85±2% R.H. Temperature: 85°C±2°C Duration: 1000hrs Min. with 100% rated current Measured at room temperature after placing for 24±2 hrs.
Moisture Resistance	Appearance: No damage. Impedance: within ±15% of initial value Inductance: within ±10% of initial value Q: Shall not exceed the specification value. RDC: within ±15% of initial value and shall not exceed the specification value	Preconditioning: Run through IR reflow for 2 times. (IPC/JEDECJ-STD-020DClassification Reflow Profiles) 1. Baked at 50°C for 25hrs, measured at room temperature after placing for 4 hrs. 2. Raise temperature to 65±2°C 90-100%RH in 2.5hrs, and keep 3 hours, cool down to 25°C in 2.5hrs. 3. Raise temperature to 65±2°C 90-100%RH in 2.5hrs, and keep 3 hours, cool down to 25°C in 2.5hrs, keep at 25°C for 2 hrs then keep at -10°C for 3 hrs 4. Keep at 25°C 80-100%RH for 15min and vibrate at the frequency of 10 to 55 Hz to 10 Hz, measure at room temperature after placing for 1~2 hrs.
Thermal shock		Preconditioning: Run through IR reflow for 2 times. (IPC/JEDECJ-STD-020DClassification Reflow Profiles) Condition for 1 cycle Step1: -40±2°C 30±5min Step2: 25±2°C ≤0.5min Step3: 125±2°C 30±5min Number of cycles: 500 Measured at room temperature after placing for 24±2 hrs.
Vibration		Preconditioning: Run through IR reflow for 2 times. (IPC/JEDECJ-STD-020DClassification Reflow Profiles) Oscillation Frequency: 10~2K~10Hz for 20 minutes Equipment: Vibration checker Total Amplitude: 1.52mm ±10% Testing Time: 12 hours (20 minutes, 12 cycles each of 3 orientations)

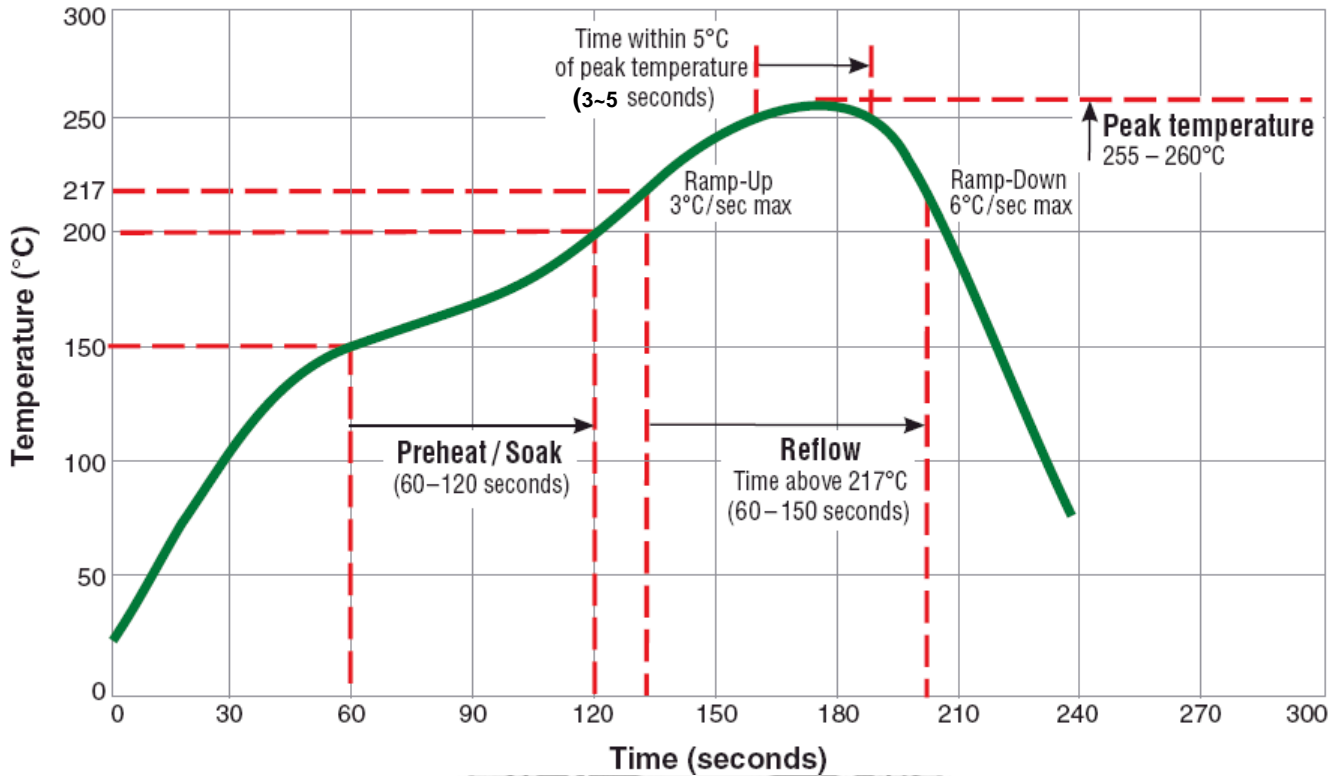
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Item	Performance	Test Condition														
Bending	Appearance: No damage. Impedance: within ±15% of initial value Inductance: within ±10% of initial value Q: Shall not exceed the specification value RDC: within ±15% of initial value and shall not exceed the specification value	Shall be mounted on a FR4 substrate of the following dimensions: ≥0805 inch(2012mm):40x100x1.2mm <0805 inch(2012mm):40x100x0.8mm Bending depth: ≥0805 inch(2012mm):1.2mm <0805 inch(2012mm):0.8mm duration of 10 sec.														
Shock		<table border="1" style="width: 100%; border-collapse: collapse;"> <thead> <tr> <th>Type</th> <th>Peak value (g's)</th> <th>Normal duration (D) (ms)</th> <th>Wave form</th> <th>Velocity change (Vi)ft/sec</th> </tr> </thead> <tbody> <tr> <td>SMD</td> <td>50</td> <td>11</td> <td>Half-sine</td> <td>11.3</td> </tr> <tr> <td>Lead</td> <td>50</td> <td>11</td> <td>Half-sine</td> <td>11.3</td> </tr> </tbody> </table>	Type	Peak value (g's)	Normal duration (D) (ms)	Wave form	Velocity change (Vi)ft/sec	SMD	50	11	Half-sine	11.3	Lead	50	11	Half-sine
Type	Peak value (g's)	Normal duration (D) (ms)	Wave form	Velocity change (Vi)ft/sec												
SMD	50	11	Half-sine	11.3												
Lead	50	11	Half-sine	11.3												
Solder ability	More than 95% of the terminal electrode should be covered with solder	Preheat: 150°C,60sec. Solder: Sn96.5% Ag3% Cu0.5% Temperature: 245±5°C Flux for lead free: Rosin. 9.5% Dip time: 4±1sec Depth: completely cover the termination														
Resistance to Soldering Heat		Depth: completely cover the termination <table border="1" style="width: 100%; border-collapse: collapse;"> <thead> <tr> <th>Temperature (°C)</th> <th>Time(s)</th> <th>Temperature ramp/immersion and emersion rate</th> <th>Number of heat cycles</th> </tr> </thead> <tbody> <tr> <td>260 ±5 (solder temp)</td> <td>10 ±1</td> <td>25mm/s ±6 mm/s</td> <td>1</td> </tr> </tbody> </table>	Temperature (°C)	Time(s)	Temperature ramp/immersion and emersion rate	Number of heat cycles	260 ±5 (solder temp)	10 ±1	25mm/s ±6 mm/s	1						
Temperature (°C)	Time(s)	Temperature ramp/immersion and emersion rate	Number of heat cycles													
260 ±5 (solder temp)	10 ±1	25mm/s ±6 mm/s	1													
Terminal Strength	Appearance: No damage. Impedance: within ±15% of initial value Inductance: within ±10% of initial value Q: Shall not exceed the specification value RDC: within ±15% of initial value and shall not exceed the specification value	Preconditioning: Run through IR reflow for 2 times. (IPC/JEDEC J-STD-020D Classification Reflow Profiles) With the component mounted on a PCB with the device to be tested, apply a force (>0805: 1kg, ≤0805:0.5kg) to the side of a device being tested. This force shall be applied for 60 +1 seconds. Also the force shall be applied gradually as not to apply a shock to the component being tested. <div style="text-align: center;"> </div>														

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11. TYPICAL RoHS REFLOW PROFILE

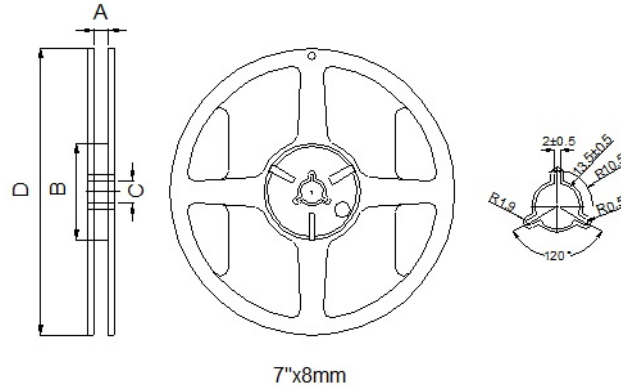
Typical RoHS Reflow Profile



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12. PACKING

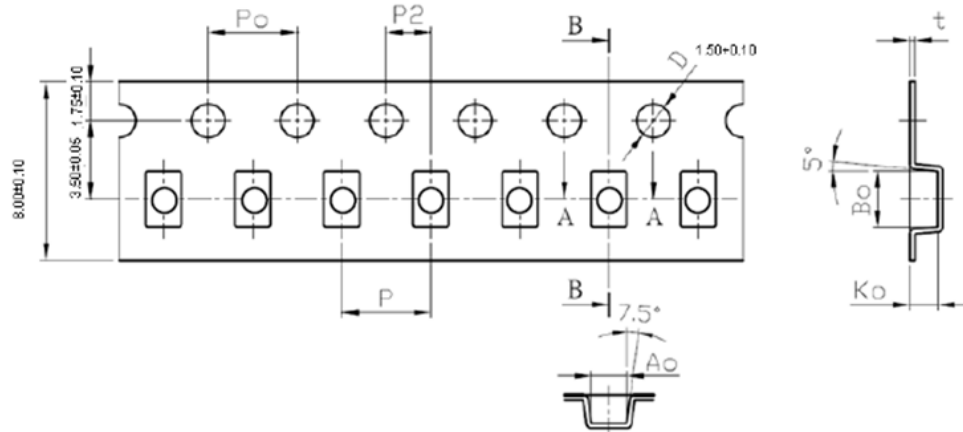
12-1 Reel Dimension



UNIT: mm

A	B	C	D
9.0±0.5	60±2	13.5±0.5	178±2

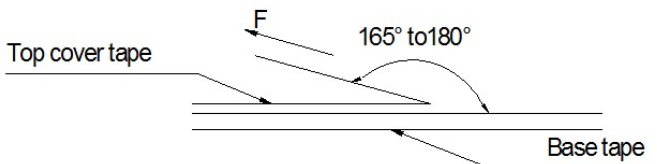
12-2 Tape Dimension



UNIT: mm

P	Po	P2	Bo	Ao	Ko	W	t
4.00±0.10	4.00±0.10	2.00±0.05	2.50±0.10	1.60±0.10	1.55±0.10	8.00±0.10	0.22±0.05

12-3 Tearing Off Force



The force for tearing off cover tape is 15 to 80 grams in the arrow direction under the following conditions.

Room Temp. (°C)	Room Humidity (%)	Room atm (hPa)	Tearing Speed mm/min
5~35	45~85	860~1060	300

12-4 Packaging Quantity: 2000 Chip/Reel

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